EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	32	257/E23.078	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/10/14 01:58
L2	5	257/E23.187	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/10/14 01:58
L3	15	257/E25.016	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/10/14 01:58
L4	1235	257/720	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/10/14 01:59
L5	2510	257/713	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/10/14 02:00
L6	1578	257/675	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/10/14 02:05
S1	3	"5,008,735".pn. or "3,280,383".pn. or "4,816,424".pn.	USPAT	OR	OFF	2007/08/31 20:01
S2	0	"560167352".pn.	JPO	OR	OFF	2007/08/31 20:01
S3	1	"56167352".pn.	JPO	OR	OFF	2007/08/31 20:01

S4	3402	(semiconductor or die or dice or chip or IC) with IGBT	USPAT	OR	ON	2008/03/24 14:35
S5	18	(semiconductor or die or dice or chip or IC) with IGBT and multi near (films or layers) with (connector or solder or contact)	USPAT	OR	ON	2008/03/24 14:37
S6	257	(semiconductor or die or dice or chip or IC) with IGBT with (connector or solder or contact)	USPAT	OR	ON	2008/03/24 14:42
S7	0	(semiconductor or die or dice or chip or IC) with IGBT same (connector or solder or contact) near lamina	USPAT	OR	ON	2008/03/24 14:42
S8	0	(semiconductor or die or dice or chip or IC) with IGBT and (connector or solder or contact) near lamina	USPAT	OR	ON	2008/03/24 14:42
S9	1	(semiconductor or die or dice or chip or IC) with IGBT and (connector or solder or contact) with lamina	USPAT	OR	ON	2008/03/24 14:43
S10	8	("4478787" | "4999336" | "5004498" | "5292478").PN. OR ("6579623").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 15:19
S11	543	(semiconductor or die or dice or chip or IC) with IGBT same (connector or solder or contact)	USPAT	OR	ON	2008/03/24 15:37
S12	37	(semiconductor or die or dice or chip or IC) with IGBT and multi near (films or layers) same (connector or solder or contact)	USPAT	OR	ON	2008/03/24 15:38
S13	19	S12 not S5	USPAT	OR	ON	2008/03/24 15:38

S14	544	(semiconductor or die or dice or chip or IC) with IGBT and (connector or solder or contact) with (coat$3 or plat$3)	USPAT	OR	ON	2008/03/24 15:40
S15	15	("4587550" | "4918514" | "5089439" | "5360985" | "5866944" | "6166402" | "6281569").PN. OR ("6495924").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 16:15
S16	23	("3825064" | "4141030" | "4426659" | "4587550" | "5106540" | "5120665" | "5399432" | "5527604" | "5543363" | "5561321" | "5695872" | "5708299" | "5781412" | "6181007").PN. OR ("6380622").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 16:55
S17	1	"6703707".pn.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:00
S18	11	("20030011054" | "20030178719" | "5594282" | "6204554" | "6215176" | "6486554" | "6590281" | "6597059").PN. OR ("6917103").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:06
S19	1	"20060087023"	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:11
S20	286	S11 not S6	USPAT	OR	ON	2008/03/24 17:13
S21	7	("20030022464" | "5471366" | "5786635" | "6208156" | "6773963" | "6791181").PN. OR ("7215020").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:18

S22	11	("20040066630" | "20050030717" | "4178630" | "5150274" | "5276586" | "5291064" | "5349237" | "5696405" | "6600651" | "6992382" | "7019395").PN. OR ("7205653").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:18
S23	27	("20030071348" | "20030106924" | "20030132530" | "3648121" | "3818584" | "4141030" | "4538170" | "4546374" | "4558345" | "4646129" | "4685987" | "4827082" | "4984061" | "5229646" | "5248853" | "5311060" | "5481137" | "5641997" | "5708299" | "5789820" | "5801445" | "5886400" | "6072240" | "6542365" | "6627997").PN. OR ("6946730").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:23
S24	1365	(semiconductor or die or dice or chip or IC) with IGBT and (connector or solder or contact) with (layers or films)	USPAT	OR	ON	2008/03/24 17:38
S25	979	S24 not S11	USPAT	OR	ON	2008/03/24 17:38
S26	3	("20060270106" | "5477611" | "7157308").PN. OR ("7220617").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:41

S27	12	("20040061163" | "20040061221" | "20040222528" | "20040245519" | "20050082668" | "20050121784" | "5198685" | "5426263" | "6137165" | "6392290" | "6529380").PN. OR ("7045884").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:43
S28	2	("4560421" | "5027180").PN. OR ("7045831").URPN.	US-PGPUB; USPAT; USOCR	OR	OFF	2008/03/24 17:48
S29	21	257/E23.078	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:33
S30	5	257/E23.187	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:35
S31	10	257/E25.016	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:36
S32	14	257/E23.006	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:36
S33	12	257/E23.109	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:37
S34	2825	257/734	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:38

S35	1261	257/727	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 13:40
S36	1186	257/720	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:04
S37	2422	257/713	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:18
S38	1510	257/675	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:29
S39	98	257/178	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:37
S40	76	257/118	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:44
S41	134	257/181	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:49
S42	3364	257/690	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/25 14:51

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